

TPS92201 1.5A 高効率同期整流降圧 LED ドライバ

1 特長

- 入力電圧範囲: 2.5V~5.5V
- 定出力電流: 1.5A
- 最大 95% の効率
- 0.1 μ A シャットダウン電流
- 220m Ω (HS) / 170m Ω (LS) MOSFET
- 最大 100% のスイッチング デューティ サイクル
- 1.5MHz のスイッチング周波数
- PWM モードを強制して低出力リップルを実現 (TPS92201)
- パワー セーブ モードでは軽負荷でも高効率を維持 (TPS92201A)
- 出力電圧範囲: 0.6V~VIN
- 100mV フィードバックレギュレーション電圧
- 1%~100% の高精度アナログ調光
- PWM 入力周波数: 20kHz~200kHz
- ソフトスタートアップを内蔵
- 過電流、LED の開放と短絡、FB 抵抗の開放と短絡に対する包括的な保護機能
- サーマル シャットダウン保護機能
- WSON および SOT563 パッケージ オプション

2 アプリケーション

- 試験および測定機器
- パワー デリバリー
- ビル オートメーション
 - スマートホーム カメラ
 - ビデオドアベル
 - IP カメラ
 - スマートドアロック
 - フラッシュライト

3 概要

TPS92201 は、2.5V~5.5V の入力範囲に対応する高効率の 1.5A 同期整流降圧型 LED ドライバです。ハイサイドとローサイドの MOSFET を内蔵しているため、高効率で小型のソリューションを実現できます。シャットダウン電流が 1 μ A と非常に低いため、バッテリー駆動アプリケーションの消費電力削減に役立ちます。

TPS92201 には、ピーク電流制御方式による適応型オフ時間が採用されています。出力リップルを最小限に抑えるため、このデバイスは電流範囲の全体にわたって、標準 1.5MHz のパルス幅変調 (PWM) モードで動作します。

TPS92201A には、ピーク電流制御方式による適応型オフ時間が採用されています。中負荷から高負荷では、デバイスはパルス幅変調 (PWM) モードで、1.5MHz のスイッチング周波数で動作します。軽負荷時には、デバイスは自動的にパルス幅変調 (PFM) へ移行し、負荷電流範囲の全体にわたって高効率を維持します。

内蔵スイッチには、最大 1.5A の定電流を供給する能力があります。アナログ調光は、PWM 入力のデューティ サイクルを 1%~100% の範囲で調整することで実現されます。可聴ノイズを回避するため、20kHz~200kHz の入力 PWM 周波数に対応できます。

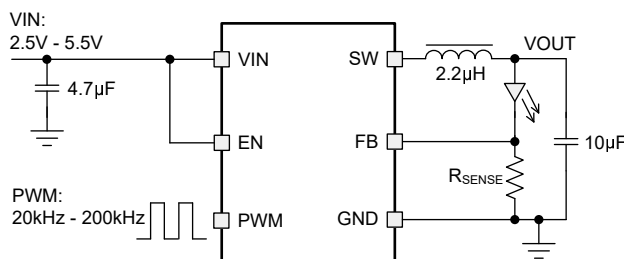
安全と保護のために、TPS92201 デバイスには、LED 開放、LED 短絡、FB 抵抗開放、FB 抵抗短絡とサーマル シャットダウンなど、完全な保護機能が実装されています。

製品情報 ⁽¹⁾

発注用製品型番	パッケージ	本体サイズ (公称)
TPS92201DRV	WSON (6)	2mm × 2mm ⁽²⁾
TPS92201ADRV	WSON (6)	
TPS92201DRL	SOT563 (6)	1.6 mm × 1.6 mm
TPS92201ADRL	SOT563 (6)	

(1) 詳細については、[セクション 11](#) を参照してください。

(2) パッケージ サイズ (長さ×幅) は公称値であり、該当する場合はピンも含まれます。



概略回路図



Table of Contents

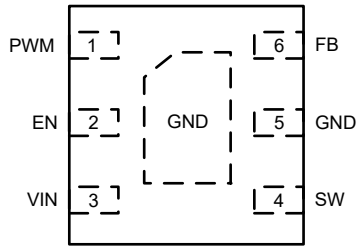
1 特長	1	8 Application and Implementation	10
2 アプリケーション	1	8.1 Application Information.....	10
3 概要	1	8.2 Typical Application.....	10
4 Device Comparison Table	2	8.3 Power Supply Recommendations.....	15
5 Pin Configuration and Functions	3	8.4 Layout.....	15
6 Specifications	4	9 Device and Documentation Support	16
6.1 Absolute Maximum Ratings.....	4	9.1 Device Support.....	16
6.2 ESD Ratings.....	4	9.2 Documentation Support.....	16
6.3 Recommended Operating Conditions.....	4	9.3 ドキュメントの更新通知を受け取る方法.....	16
6.4 Thermal Information.....	4	9.4 サポート・リソース.....	16
6.5 Electrical Characteristics.....	5	9.5 Trademarks.....	16
6.6 Typical Characteristics.....	6	9.6 静電気放電に関する注意事項.....	16
7 Detailed Description	7	9.7 用語集.....	16
7.1 Overview.....	7	10 Revision History	17
7.2 Functional Block Diagram.....	7	11 Mechanical, Packaging, and Orderable Information	18
7.3 Feature Description.....	7		
7.4 Device Functional Modes.....	9		

4 Device Comparison Table

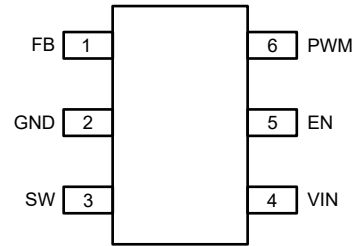
PART NUMBER	MATERIAL	POWER SAVE MODE	PACKAGE
TPS92200	TPS92201DRVR	No	WS0N-6
	TPS92201MDRVR ⁽¹⁾		
	TPS92201DRLR		SOT563-6
	TPS92201MDRLR ⁽¹⁾		
TPS92201A	TPS92201ADRVR	Yes	WS0N-6
	TPS92201AMDRVR ⁽¹⁾		
	TPS92201ADRLR		SOT563-6
	TPS92201AMDRLR ⁽¹⁾		

(1) Extended Temperature devices, supporting –55°C to approximately 125°C operating ambient temperature.

5 Pin Configuration and Functions



☒ 5-1. DRV Package 6-Pin WSON Top View



☒ 5-2. DRL Package 6-Pin SOT563 Top View

NAME	PIN NUMBER		I/O/PWR	DESCRIPTION
	DRV	DRL		
PWM	1	6	I	PWM input. LED output current is adjusted according to the PWM input duty cycle.
EN	2	5	I	Device enable input. Logic high enables the device, logic low disables the device and turns the device into shutdown. Do not leave floating.
VIN	3	4	PWR	Power supply input.
SW	4	3	PWR	Switch pin. Connecting the internal FET switches and inductor terminal.
GND	5	2	PWR	Power ground.
FB	6	1	I	Feedback pin for the internal control loop. Connect this pin to an external resistor to set output current.

6 Specifications

6.1 Absolute Maximum Ratings

over operating ambient temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
Voltage	VIN, EN, PWM	-0.3	6	V
	SW (DC)	-0.3	VIN + 0.3	V
	SW (AC, 10ns transient)	-3	9	V
	FB	-0.3	5.5	V
Operating junction temperature, T _J		-40	150	°C
Storage temperature, T _{stg}		-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000	V
		Charged-device model (CDM), per ANSI/ESDA/JEDEC JS-002 ⁽²⁾	±500	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating ambient temperature range (unless otherwise noted)

		MIN	MAX	UNIT
Input stage	V _{IN}	2.5	5.5	V
	V _{EN}	-0.1	6	V
	V _{PWM}	-0.1	6	V
Output stage	V _{OUT}		V _{IN}	V
	I _{OUT}		1.5	A
Peripheral component	Effective inductance	2.2	4.7	μH
	Effective capacitance			μF
Temperature	Operating Ambient temperature, T _A	-40	85	°C
	Operating Junction temperature, T _J	-40	125	°C

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TPS92201, TPS92201A		UNIT
		DRL (SOT563)	DRV (WSON-6)	
		6 PINS	6 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	152	82.6	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	73.1	106.5	°C/W
R _{θJB}	Junction-to-board thermal resistance	41.3	45.8	°C/W
ψ _{JT}	Junction-to-top characterization parameter	2.1	7.7	°C/W
ψ _{JB}	Junction-to-board characterization parameter	40.7	45.7	°C/W

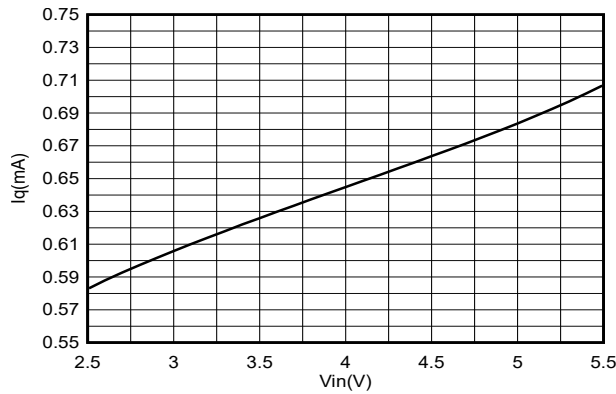
- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

6.5 Electrical Characteristics

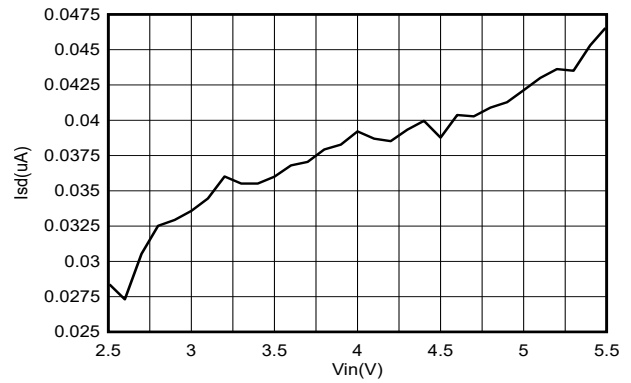
$V_{IN} = 2.5V$ to $5.5V$, $T_A = -40^{\circ}C$ to $+85^{\circ}C$ ($T_A = -55^{\circ}C$ to $+125^{\circ}C$ for TPS92201MDRVR and TPS92201AMDRVR and for the TPS92201MDRLR and TPS92201AMDRLR); Typical values are at $T_A = 25^{\circ}C$ (unless otherwise specified)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
INPUT SUPPLY						
V_{IN}	Input voltage range		2.5		5.5	V
V_{IN_UVLO}	V_{IN} undervoltage lockout	Falling V_{IN}	2.1	2.2		V
		Rising V_{IN}		2.3	2.4	V
	Hysteresis			0.1		V
I_{SD}	Shutdown current into V_{IN}	$V_{IN} = 3.6V, V_{EN} = 0$		0.1	0.5	μA
I_{SD_ET}	Shutdown current into V_{IN}	$V_{IN} = 3.6V, V_{EN} = 0$ (TPS92201MDRVR, TPS92201AMDRVR, TPS92201MDRLR and TPS92201AMDRLR)		0.1	1.75	μA
I_Q	Quiescent current into V_{IN}	$V_{IN} = 3.6V, V_{EN} = 2V, V_{FB}=0V$, Not switching (TPS92201)	450	520	600	μA
		$V_{IN} = 3.6V, V_{EN} = 2V, V_{FB} = 0V$, Not switching (TPS92201A)	520	630	720	μA
LOGIC INTERFACE						
V_{EN_H}	High-level threshold voltage of EN				1.2	V
V_{EN_L}	Low-level threshold voltage of EN		0.4			V
V_{IH_PWM}	High-level threshold voltage of PWM				1	V
V_{IL_PWM}	Low-level threshold voltage of PWM		0.7			V
t_{EN_ON}	EN minimum on time to enable device					μS
t_{EN_OFF}	EN minimum off time to disable device					μS
t_{PWM_ON}	PWM minimum on time when dimming the output current				5	μS
f_{PWM}	PWM input frequency		20		200	kHz
D_{PWM}	PWM input duty cycle		1		100	%
I_{LKG}	Leakage current of EN pin	$V_{IN} = 5.5V, V_{EN} = 5.5V, V_{PWM} = 5.5V$,			1	μA
I_{LKG}	Leakage current of PWM pin	$V_{IN} = 5.5V, V_{EN} = 5.5V, V_{PWM} = 5.5V$,			0.5	μA
OUTPUT STAGE						
V_{FB_REF}	FB pin regulation voltage at maximum duty cycle	PWM = 100%, $I_{OUT} = 500mA$	92	100	104	mV
	FB pin regulation voltage at 50% duty cycle	PWM = 50%, $I_{OUT} = 0mA(TM)$, $F_{PWM}=20KHz$	-8%	50	+8%	mV
	FB pin regulation voltage at 50% duty cycle	PWM = 50%, $I_{OUT} = 0mA(TM)$, $F_{PWM}=200KHz$	-10%	50	+10%	mV
	FB pin regulation voltage at 5% duty cycle	PWM = 5%, $I_{OUT} = 500mA$		5		mV
	FB pin regulation voltage at 1% duty cycle	PWM = 1%, $I_{OUT} = 500mA$		1		mV
R_{HS}	High-side FET on resistance			220	330	m Ω
R_{LS}	Low-side FET on resistance			170	300	m Ω
f_{SW}	Switching frequency			1.5		MHz
D_{max}	Maximum switching duty cycle			100		%
I_{LIM_HS}	High-side current limit		1.9	2.16		A

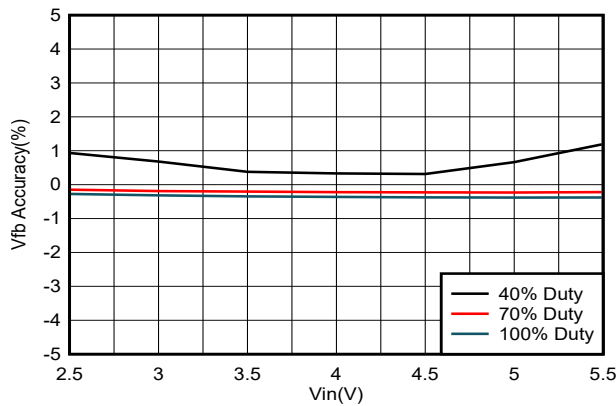
6.6 Typical Characteristics



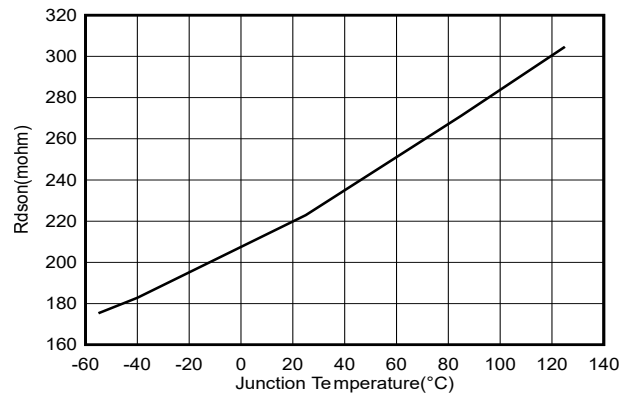
6-1. Quiescent Current vs Input Voltage



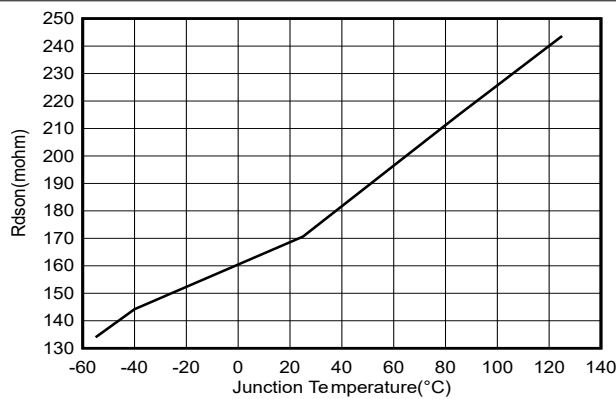
6-2. Shutdown Current vs Input Voltage



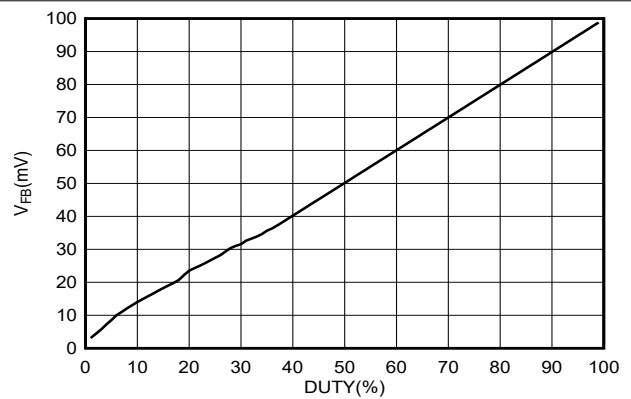
6-3. FB Voltage Accuracy



6-4. High-Side FET On Resistance vs Junction Temperature



6-5. Low-Side FET On Resistance vs Junction Temperature



6-6. PWM duty cycle vs FB voltage

7 Detailed Description

7.1 Overview

The TPS92201 is a high-efficiency 1.5A synchronous buck-type LED driver with 2.5V to 5.5V input range. The device operates at typically 1.5MHz pulse width modulation (PWM) mode in full current range. In addition, TPS92201A can support Power Save Mode, the device operates in pulse width modulation (PWM) mode with 1.5MHz switching frequency at heavy load, similar as TPS92201. But at light load, the device automatically enters pulse frequency modulation (PFM) to maintain high efficiency over the entire load current range. In Power Save Mode, the converter reduces switching frequency and minimizes current consumption, the output voltage rises slightly above the nominal output voltage. This effect is minimized by increasing the output capacitor.

The integrated switches for both devices have the capability to deliver up to 1.5A constant current and no need for external Schottky diode. Analog dimming is achieved by adjusting the duty cycle of the PWM in 1% to 100% range. Full protection methods are implemented including LED open, LED short, FB resistor open, FB resistor short and thermal shutdown.

7.2 Functional Block Diagram

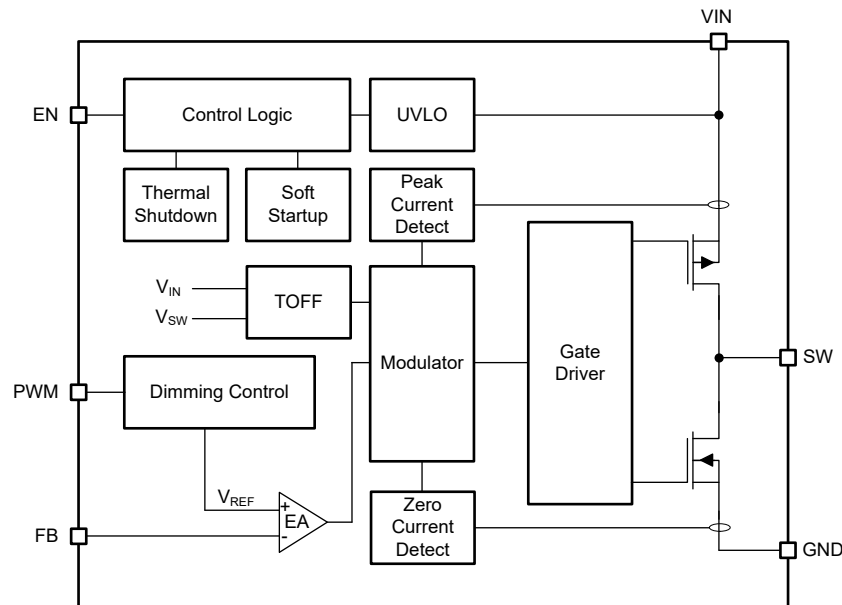


図 7-1. TPS92201 Functional Block Diagram

7.3 Feature Description

7.3.1 Adaptive Off-time Control

Adaptive off-time with peak current control scheme is used in the device. The device operates at typically 1.5MHz pulse width modulation (PWM) mode in full current range. At medium to heavy load, the device operates in pulse width modulation (PWM) mode with 1.5MHz switching frequency. At light load, the device automatically enters pulse frequency modulation (PFM) to maintain high efficiency over the entire load current range. Based on the VIN/VOUT ratio, a simple circuit sets the required off time for the low-side MOSFET. The switching frequency relatively constant regardless of the variation of input voltage, output voltage, and load current.

7.3.2 Power Save Mode

TPS92201A automatically enters Power Save Mode to improve efficiency at light load when the inductor current becomes discontinuous. In Power Save Mode, the converter reduces switching frequency and minimizes current consumption. In Power Save Mode, the output voltage rises slightly above the nominal output voltage. This effect is minimized by increasing the output capacitor.

7.3.3 Soft Startup

After enabling the device, internal soft startup circuitry ramps up the output voltage which reaches nominal output voltage during a startup time. Output current rises smoothly and excessive inrush current is avoided. In battery-power system, the soft startup prevents extra voltage drop on primary power supply with high internal impedance. The internal soft startup period is xx ms typically.

7.3.4 Low Dropout Operation

The device offers a low input-to-output voltage differential by entering 100% switching duty cycle mode. In this mode, the high-side MOSFET switch is constantly turned on and the low-side MOSFET is switched off. The minimum input voltage to maintain output regulation, depending on the load current and output voltage, is calculated as:

$$V_{IN_MIN} = V_{FB} + V_{F_IOUT} + I_{OUT} \times (R_{DS_ON} + R_L) \quad (1)$$

where

- V_{FB} is the feedback reference voltage, which is typically 100mV
- V_{F_IOUT} is the LED forward voltage at output current
- I_{OUT} is the output current setting
- R_{DS_ON} is the high-side FET resistance when turning on
- R_L is the inductor ohmic resistance DCR

7.3.5 LED Current Setting

The LED current is set by the external resistor between the FB pin and GND, calculated as:

$$I_{LED} = \frac{V_{FB}}{R_{SENSE}} \quad (2)$$

where

- V_{FB} is the feedback reference voltage, which is typically 100mV
- R_{SENSE} is the resistance between FB and GND

7.3.6 Voltage Reference

The feedback reference produces a precise $\pm 5\%$ voltage reference over whole temperature range when the PWM duty cycle is 100%, which is typically 100mV. In analog dimming mode, the feedback voltage is proportional to the duty cycle of PWM input as shown in [Figure 7-2](#).

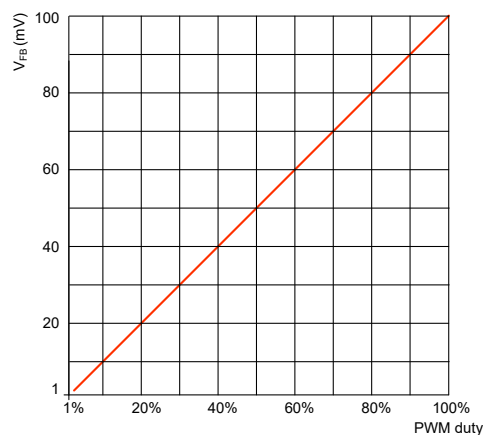


Figure 7-2. FB voltage with PWM duty cycle

7.3.7 Switch Current Limit

The switch current limit prevents the device from high inductor current and drawing excessive current from battery or input voltage supply. Excessive current might occur with a heavy load or shorted output circuit condition. The device adopts the peak current control by sensing the current of the high-side switch. Once the high-side switch current limit is reached, the high-side switch is turned off and low-side switch is turned on to discharge the inductor current with an adaptive off-time.

7.3.8 Fault Behaviors

The TPS92201 is protected by high-side current limitation in different fault conditions, such as LED open and short, sense resistor open and short. No matter the fault happens before startup or during operation, the device can stay safety.

表 7-1. Fault protection conditions

Fault	Condition	Behavior
LED open	V_{FB} is driven close to 0	VOUT keeps increasing to VIN. and The high-side switch keeps turn on.
LED anode short to cathode	V_{FB} is driven to VOUT quickly, then	VFB is driven to VOUT quickly, the device keeps switching by minimum on-time.
LED anode short to GND	V_{FB} is driven close to 0	high-side switch current limit triggered
FB resistor open	V_{FB} is driven to VOUT - Vf	The device keeps switching by the minimum on-time
FB short to GND	V_{FB} is driven close to 0	VFB is driven close to 0. Current limit is triggered.

7.3.9 Under Voltage Lockout

To avoid mis-operation of the device at low input voltages, under voltage lockout is implemented that shuts down the device at voltages lower than V_{UVLO} with V_{HYS_UVLO} hysteresis.

7.3.10 Thermal Shutdown

The device enters thermal shutdown once the junction temperature exceeds the thermal shutdown rising threshold, T_{JSD} . Once the junction temperature falls below the falling threshold, the device returns to normal operation automatically.

7.4 Device Functional Modes

7.4.1 Enabling/Disabling the Device

The device is enabled by setting the EN input to a logic High. Accordingly, a logic Low disables the device. If the device is enabled, the internal power stage starts switching and regulates the output current to the set value. The EN input must be terminated and should not be floating.

8 Application and Implementation

注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The TPS92201 device is typically used as buck-type LED driver to drive IR or white LEDs from a 2.5V to 5.5V input.

8.2 Typical Application

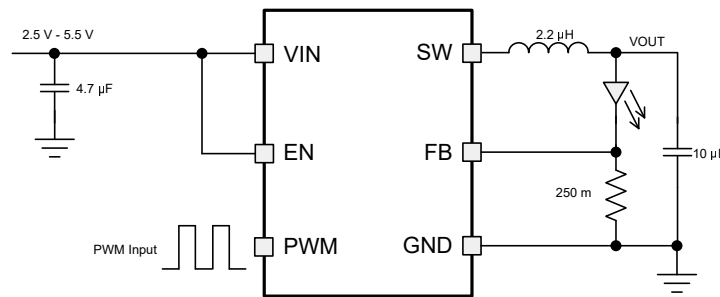


図 8-1. TPS92201 400mA Output Application

8.2.1 Design Requirements

For this design example, use the parameters listed in 表 8-1 as the input parameters.

表 8-1. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
Input voltage	2.5V to 5.5V
Output voltage	1.9V (1.8V Vf + 0.1V VFB)
Maximum output current	400mA

表 8-2 lists the components used for the example.

表 8-2. List of Components

REFERENCE	DESCRIPTION	MANUFACTURER ⁽¹⁾
C1	4.7µF, Ceramic Capacitor, 10V, X7R, size 0805, GRM21BR71A475KA73L	Murata
C2	10µF, Ceramic Capacitor, 10V, X7R, size 0805, GRM21BR71A106KE51L	Murata
L1	2.2µH, Power Inductor, SDER041H-2R2MS	Cyntec
R1,R2,R3	Chip resistor, 1%, size 0603	Std.
C3	Optional, 6.8pF if it is needed	Std.

(1) See [Third-party Products Disclaimer](#)

8.2.2 Detailed Design Procedure

8.2.2.1 Custom Design With WEBENCH® Tools

[Click here](#) to create a custom design using the TPS92201 device with the WEBENCH® Power Designer.

1. Start by entering the input voltage (V_{IN}), output voltage (V_{OUT}), and output current (I_{OUT}) requirements.
2. Optimize the design for key parameters such as efficiency, footprint, and cost using the optimizer dial.
3. Compare the generated design with other possible solutions from Texas Instruments.

The WEBENCH Power Designer provides a customized schematic along with a list of materials with real-time pricing and component availability.

In most cases, these actions are available:

- Run electrical simulations to see important waveforms and circuit performance
- Run thermal simulations to understand board thermal performance
- Export customized schematic and layout into popular CAD formats
- Print PDF reports for the design, and share the design with colleagues

Get more information about WEBENCH tools at www.ti.com/WEBENCH.

8.2.2.2 Setting the Output Voltage

When sizing R2, in order to achieve low current consumption and acceptable noise sensitivity, use a maximum of 200kΩ for R2. Larger currents through R2 improve noise sensitivity and output voltage accuracy but increase current consumption.

$$V_{OUT} = V_{FB} \times \left(1 + \frac{R1}{R2}\right) = 0.6V \times \left(1 + \frac{R1}{R2}\right) \quad (3)$$

A feed forward capacitor, C3 improves the loop bandwidth to make a fast transient response. 6.8pF capacitance is recommended for R2 of 100kΩ resistance. A more detailed discussion on the optimization for stability vs. transient response can be found in [SLVA289](#).

8.2.2.3 Output Filter Design

The inductor and output capacitor together provide a low-pass filter. To simplify this process, [表 8-3](#) outlines possible inductor and capacitor value combinations. Checked cells represent combinations that are proven for stability by simulation and lab test. Further combinations should be checked for each individual application.

表 8-3. Matrix of Output Capacitor and Inductor Combinations

V_{OUT} [V]	L [μ H] ⁽¹⁾	C_{OUT} [μ F] ⁽²⁾				
		4.7	10	22	2x 22	100
$0.6 \leq V_{OUT} < 1.2$	1				+	
	2.2				++ ⁽³⁾	
$1.2 \leq V_{OUT} < 1.8$	1			+	+	
	2.2			++ ⁽³⁾	+	
$1.8 \leq V_{OUT}$	1		+	+	+	
	2.2		++ ⁽³⁾	+	+	

- (1) Inductor tolerance and current de-rating is anticipated. The effective inductance can vary by +20% and -30%.
- (2) Capacitor tolerance and bias voltage de-rating is anticipated. The effective capacitance can vary by +20% and -50%.
- (3) This LC combination is the standard value and recommended for most applications.

8.2.2.4 Inductor Selection

The main parameters for inductor selection is inductor value and then saturation current of the inductor. To calculate the maximum inductor current under static load conditions, 式 4 is given:

$$I_{L,MAX} = I_{OUT,MAX} + \frac{\Delta I_L}{2}$$

$$\Delta I_L = V_{OUT} \times \frac{1 - \frac{V_{OUT}}{V_{IN}}}{L \times f_{SW}} \quad (4)$$

where:

- $I_{OUT,MAX}$ is the maximum output current
- ΔI_L is the inductor current ripple
- f_{SW} is the switching frequency
- L is the inductor value

It is recommended to choose a saturation current for the inductor that is approximately 20% to 30% higher than $I_{L,MAX}$. In addition, DC resistance and size should also be taken into account when selecting an appropriate inductor.

8.2.2.5 Input and Output Capacitor Selection

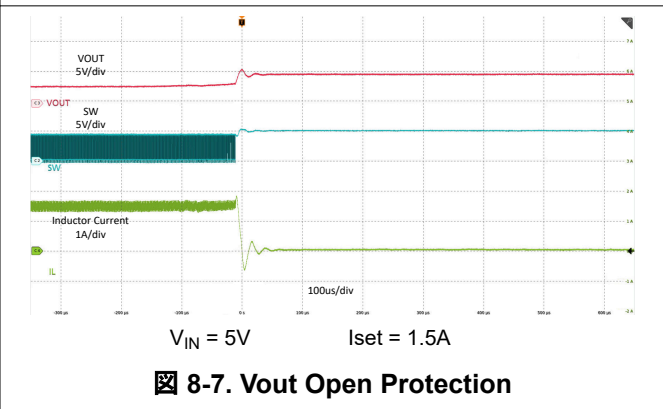
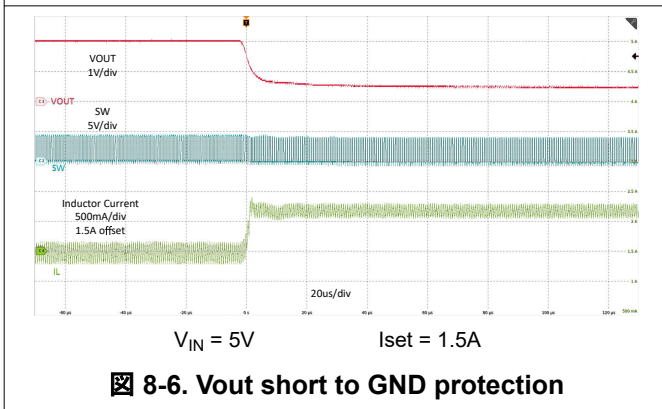
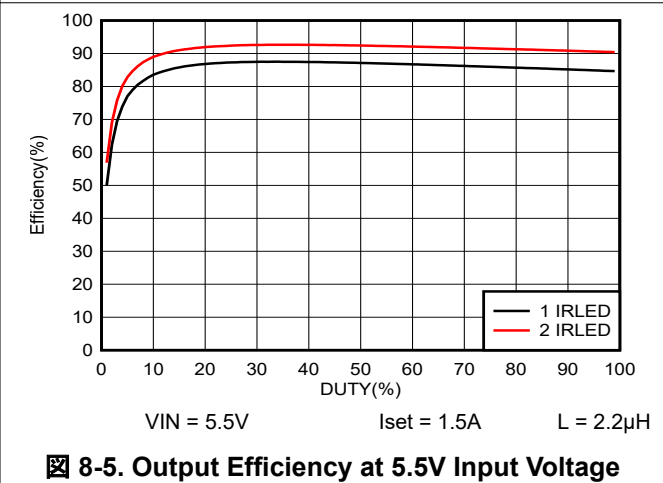
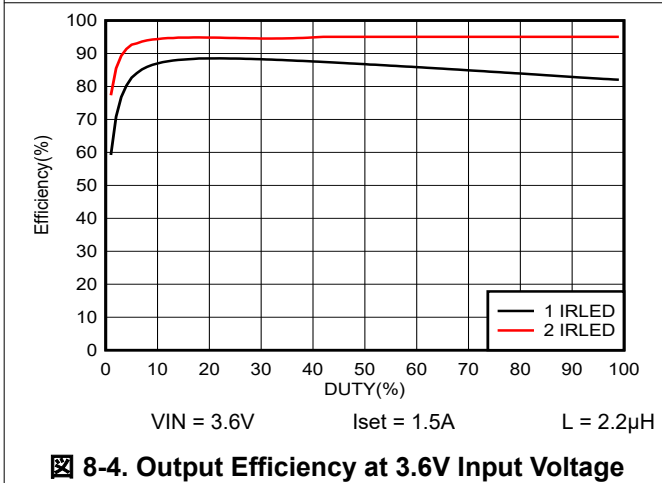
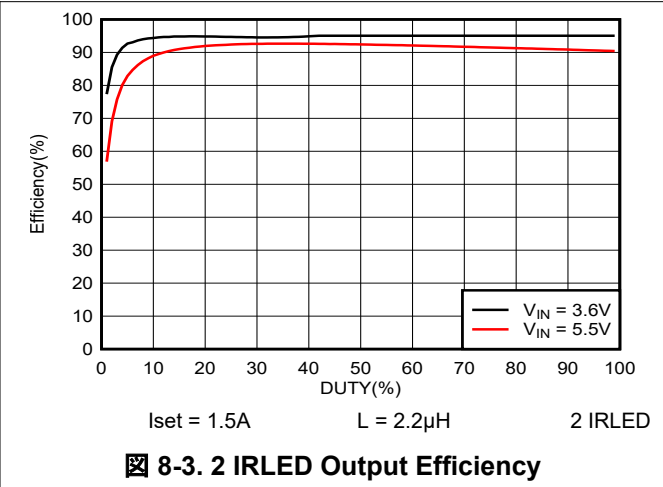
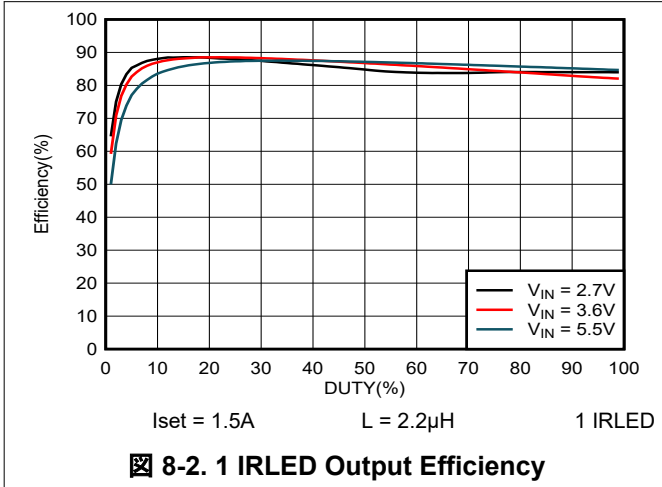
The architecture of the TPS92201 allows use of tiny ceramic-type output capacitors with low equivalent series resistance (ESR). These capacitors provide low output voltage ripple and are thus recommended. To keep its resistance up to high frequencies and to achieve narrow capacitance variation with temperature, it is recommended to use X7R or X5R dielectric.

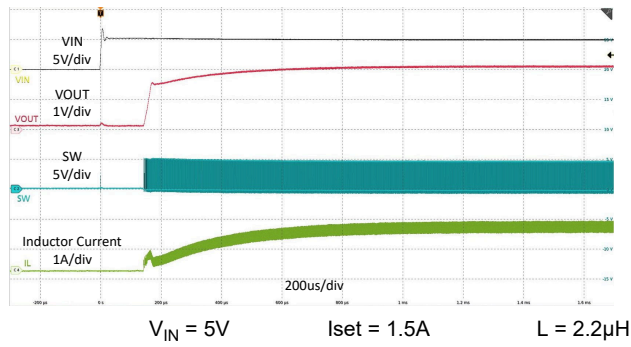
The input capacitor is the low impedance energy source for the converter that helps provide stable operation. A low ESR multilayer ceramic capacitor is recommended for best filtering. For most applications, 4.7 μ F input capacitance is sufficient; a larger value reduces input voltage ripple.

The TPS92201 is designed to operate with an output capacitor of 10 μ F to 47 μ F, as outlined in 表 8-3.

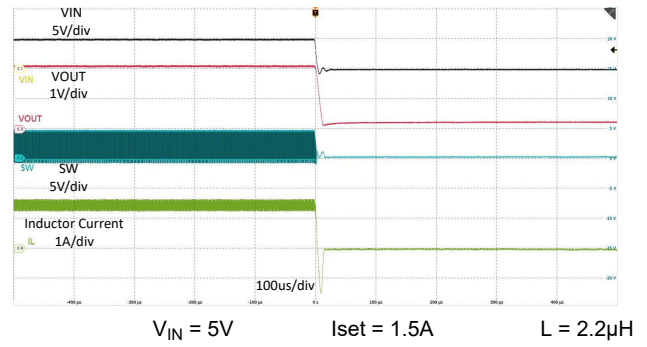
8.2.3 Application Performance Curves

$V_{IN} = 5V$, $V_{OUT} = 1.8V$, $L = 2.2\mu H$, $T_A = 25^\circ C$, unless otherwise noted.

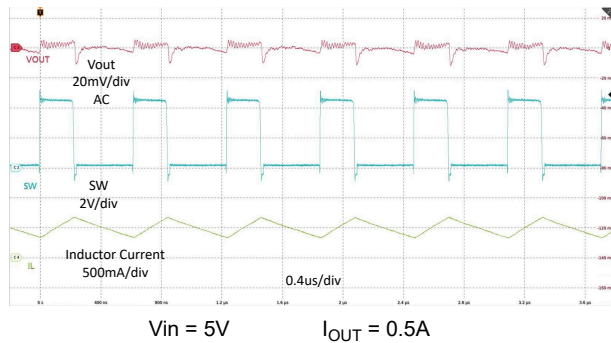




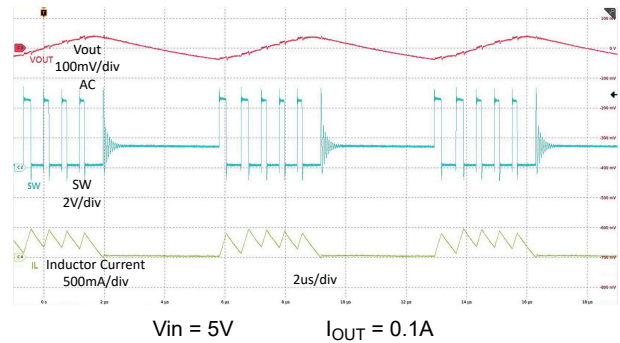
8-8. VIN Control Start Up with Load



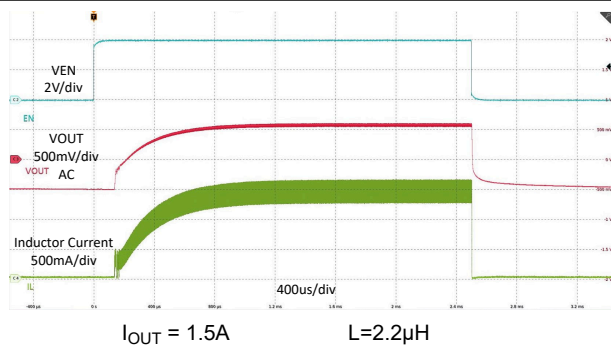
8-9. VIN Control Shutdown with Load



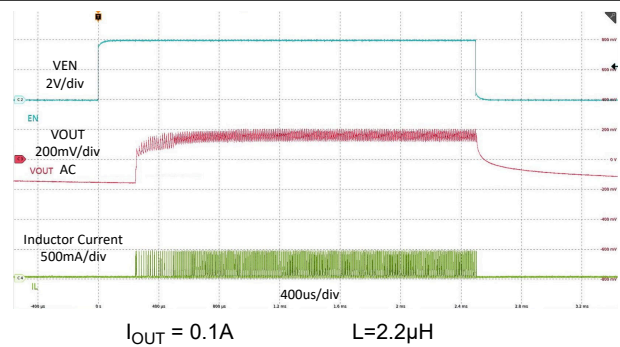
8-10. PWM Operation



8-11. Power Save Mode Operation



8-12. EN Control Startup with Load



8-13. EN Control Startup with Load

8.3 Power Supply Recommendations

The power supply to the TPS92201 must have a current rating according to the supply voltage, output voltage and output current.

8.4 Layout

8.4.1 Layout Guidelines

The PCB layout is an important step to maintain the high performance of the TPS92201 device.

- The input/output capacitors and the inductor should be placed as close as possible to the IC. This keeps the power traces short. Routing these power traces direct and wide results in low trace resistance and low parasitic inductance.
- The low side of the input and output capacitors must be connected properly to the power GND to avoid a GND potential shift.
- The sense traces connected to FB are signal traces. Special care should be taken to avoid noise being induced. Keep these traces away from SW nodes.
- GND layers might be used for shielding.

8.4.2 Layout Example

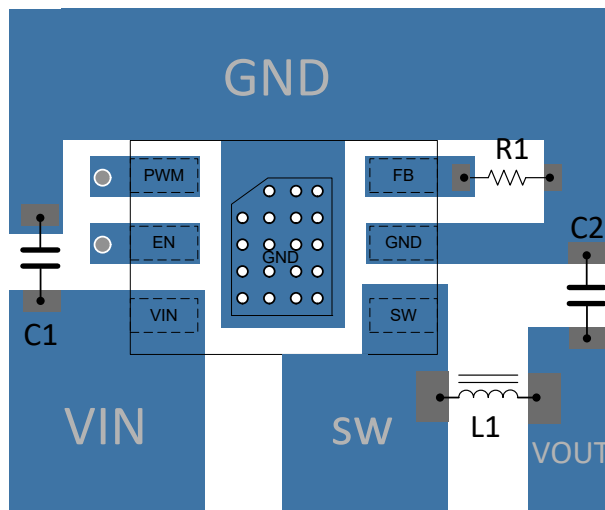


図 8-14. TPS92201WSON Layout

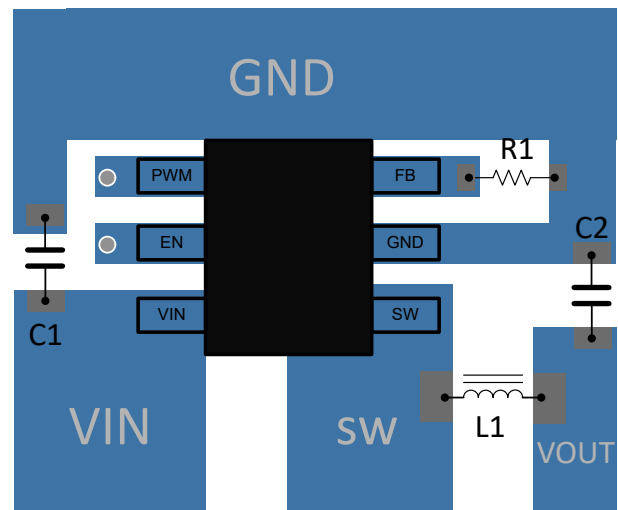


図 8-15. TPS92201SOT Layout

8.4.3 Thermal Considerations

Implementation of integrated circuits in low-profile and fine-pitch surface-mount packages typically requires special attention to power dissipation. Many system-dependent issues such as thermal coupling, airflow, convection surfaces, and the presence of other heat-generating components affect the power dissipation limits of a given component.

Two basic approaches for enhancing thermal performance are listed below:

- Improving the power dissipation capability of the PCB design
- Introducing airflow in the system

For more details on how to use the thermal parameters, see the application notes: Thermal Characteristics Application Notes [SZZA017](#) and [SPRA953](#).

9 Device and Documentation Support

9.1 Device Support

9.1.1 Custom Design With WEBENCH® Tools

[Click here](#) to create a custom design using the TPS92201 device with the WEBENCH® Power Designer.

1. Start by entering the input voltage (V_{IN}), output voltage (V_{OUT}), and output current (I_{OUT}) requirements.
2. Optimize the design for key parameters such as efficiency, footprint, and cost using the optimizer dial.
3. Compare the generated design with other possible solutions from Texas Instruments.

The WEBENCH Power Designer provides a customized schematic along with a list of materials with real-time pricing and component availability.

In most cases, these actions are available:

- Run electrical simulations to see important waveforms and circuit performance
- Run thermal simulations to understand board thermal performance
- Export customized schematic and layout into popular CAD formats
- Print PDF reports for the design, and share the design with colleagues

Get more information about WEBENCH tools at www.ti.com/WEBENCH.

9.2 Documentation Support

9.2.1 Related Documentation

Semiconductor and IC Package Thermal Metrics Application Report (SPRA953)

Thermal Characteristics of Linear and Logic Packages Using JEDEC PCB Designs Application Report (SZZA017)

9.3 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、www.tij.co.jp のデバイス製品フォルダを開いてください。[通知] をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取ることができます。変更の詳細については、改訂されたドキュメントに含まれている改訂履歴をご覧ください。

9.4 サポート・リソース

テキサス・インスツルメンツ E2E™ サポート・フォーラムは、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計に必要な支援を迅速に得ることができます。

リンクされているコンテンツは、各寄稿者により「現状のまま」提供されるものです。これらはテキサス・インスツルメンツの仕様を構成するものではなく、必ずしもテキサス・インスツルメンツの見解を反映したものではありません。テキサス・インスツルメンツの[使用条件](#)を参照してください。

9.5 Trademarks

テキサス・インスツルメンツ E2E™ is a trademark of Texas Instruments.

すべての商標は、それぞれの所有者に帰属します。

9.6 静電気放電に関する注意事項



この IC は、ESD によって破損する可能性があります。テキサス・インスツルメンツは、IC を取り扱う際には常に適切な注意を払うことを推奨します。正しい取り扱いおよび設置手順に従わない場合、デバイスを破損するおそれがあります。

ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

9.7 用語集

[テキサス・インスツルメンツ用語集](#)

この用語集には、用語や略語の一覧および定義が記載されています。

10 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision A (August 2024) to Revision B (August 2024) Page

- SOT563-6 パッケージ オプションを記載するようにドキュメントを更新。..... 1
-

Changes from Revision * (November 2023) to Revision A (August 2024) Page

- 注文用型番のマーケティング ステータスを「製品プレビュー」から「量産データ」に更新..... 1
 - Updated Device Comparison table to include the DRL package.....2
-

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

重要なお知らせと免責事項

テキサス・インスツルメンツは、技術データと信頼性データ (データシートを含みます)、設計リソース (リファレンス デザインを含みます)、アプリケーションや設計に関する各種アドバイス、Web ツール、安全性情報、その他のリソースを、欠陥が存在する可能性のある「現状のまま」提供しており、商品性および特定目的に対する適合性の黙示保証、第三者の知的財産権の非侵害保証を含むいかなる保証も、明示的または黙示的にかかわらず拒否します。

これらのリソースは、テキサス・インスツルメンツ製品を使用する設計の経験を積んだ開発者への提供を意図したものです。(1) お客様のアプリケーションに適した テキサス・インスツルメンツ製品の選定、(2) お客様のアプリケーションの設計、検証、試験、(3) お客様のアプリケーションに該当する各種規格や、その他のあらゆる安全性、セキュリティ、規制、または他の要件への確実な適合に関する責任を、お客様のみが単独で負うものとします。

上記の各種リソースは、予告なく変更される可能性があります。これらのリソースは、リソースで説明されている テキサス・インスツルメンツ製品を使用するアプリケーションの開発の目的でのみ、テキサス・インスツルメンツはその使用をお客様に許諾します。これらのリソースに関して、他の目的で複製することや掲載することは禁止されています。テキサス・インスツルメンツや第三者の知的財産権のライセンスが付与されている訳ではありません。お客様は、これらのリソースを自身で使用した結果発生するあらゆる申し立て、損害、費用、損失、責任について、テキサス・インスツルメンツおよびその代理人を完全に補償するものとし、テキサス・インスツルメンツは一切の責任を拒否します。

テキサス・インスツルメンツの製品は、[テキサス・インスツルメンツの販売条件](#)、または [ti.com](https://www.ti.com) やかかる テキサス・インスツルメンツ製品の関連資料などのいずれかを通じて提供する適用可能な条項の下で提供されています。テキサス・インスツルメンツがこれらのリソースを提供することは、適用されるテキサス・インスツルメンツの保証または他の保証の放棄の拡大や変更を意味するものではありません。

お客様がいかなる追加条項または代替条項を提案した場合でも、テキサス・インスツルメンツはそれらに異議を唱え、拒否します。

郵送先住所: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

Copyright © 2024, Texas Instruments Incorporated

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS92201ADRLR	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	3GDH
TPS92201ADRLR.A	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	3GDH
TPS92201ADRVR	Active	Production	WSON (DRV) 6	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	34MH
TPS92201ADRVR.A	Active	Production	WSON (DRV) 6	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	34MH
TPS92201AMDRLR	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-55 to 125	3GEH
TPS92201AMDRV	Active	Production	WSON (DRV) 6	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	3CZH
TPS92201AMDRV.A	Active	Production	WSON (DRV) 6	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	3CZH
TPS92201DRLR	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	3GCH
TPS92201DRV	Active	Production	WSON (DRV) 6	3000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	34LH
TPS92201DRV.A	Active	Production	WSON (DRV) 6	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	34LH
TPS92201MDRLR	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-55 to 125	3GFH
TPS92201MDRV	Active	Production	WSON (DRV) 6	3000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-55 to 125	3CXH
TPS92201MDRV.A	Active	Production	WSON (DRV) 6	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	3CXH

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS92201ADRLR	SOT-5X3	DRL	6	4000	180.0	8.4	1.8	1.8	0.75	4.0	8.0	Q3
TPS92201AMDRLR	SOT-5X3	DRL	6	4000	180.0	8.4	1.8	1.8	0.75	4.0	8.0	Q3
TPS92201AMDRV	WSON	DRV	6	3000	180.0	8.4	2.3	2.3	1.15	4.0	8.0	Q2
TPS92201DRLR	SOT-5X3	DRL	6	4000	180.0	8.4	1.8	1.8	0.75	4.0	8.0	Q3
TPS92201DRV	WSON	DRV	6	3000	178.0	8.4	2.3	2.3	1.15	4.0	8.0	Q2
TPS92201MDRLR	SOT-5X3	DRL	6	4000	180.0	8.4	1.8	1.8	0.75	4.0	8.0	Q3
TPS92201MDRV	WSON	DRV	6	3000	180.0	8.4	2.3	2.3	1.15	4.0	8.0	Q2

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS92201ADRLR	SOT-5X3	DRL	6	4000	210.0	185.0	35.0
TPS92201AMDRLR	SOT-5X3	DRL	6	4000	210.0	185.0	35.0
TPS92201AMDRVR	WSON	DRV	6	3000	210.0	185.0	35.0
TPS92201DRLR	SOT-5X3	DRL	6	4000	210.0	185.0	35.0
TPS92201DRVR	WSON	DRV	6	3000	208.0	191.0	35.0
TPS92201MDRLR	SOT-5X3	DRL	6	4000	210.0	185.0	35.0
TPS92201MDRVR	WSON	DRV	6	3000	210.0	185.0	35.0

GENERIC PACKAGE VIEW

DRV 6

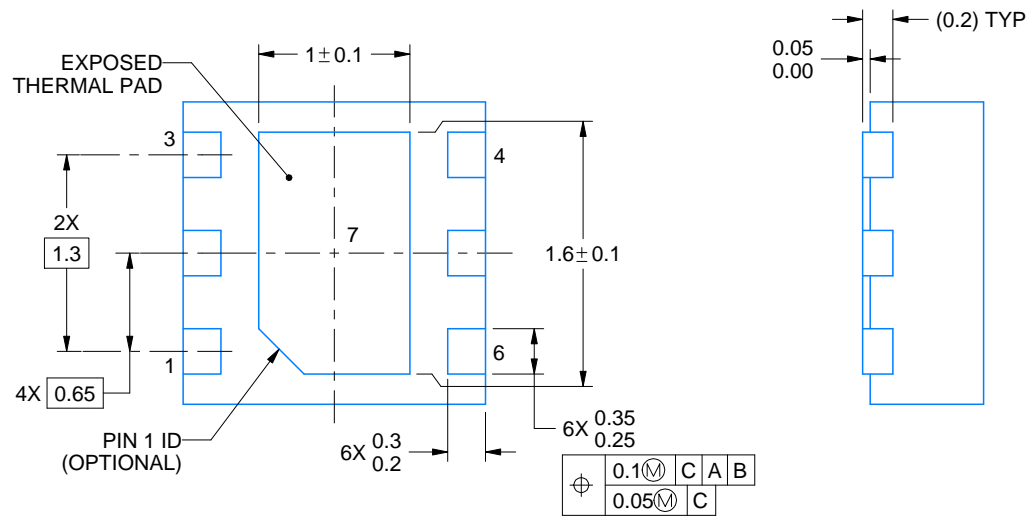
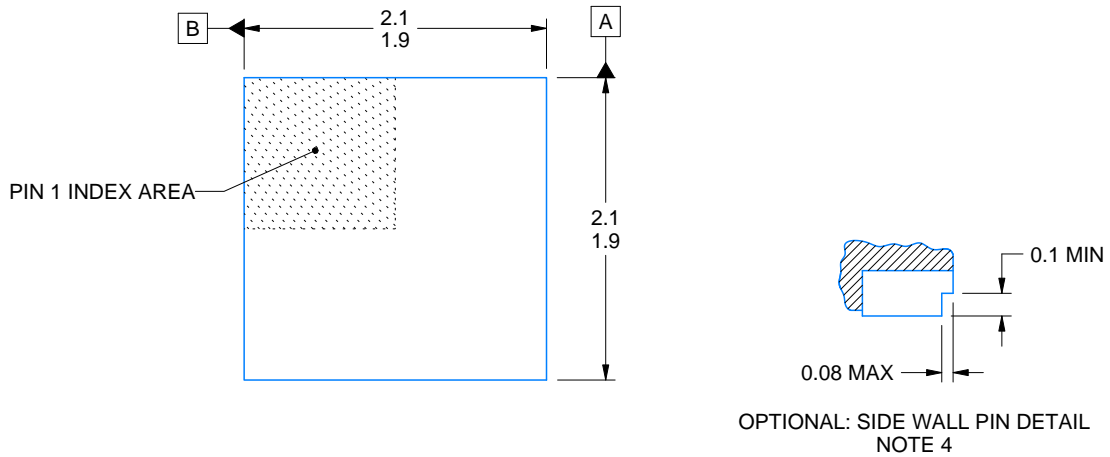
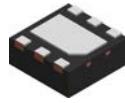
WSON - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4206925/F



4222173/C 11/2025

NOTES:

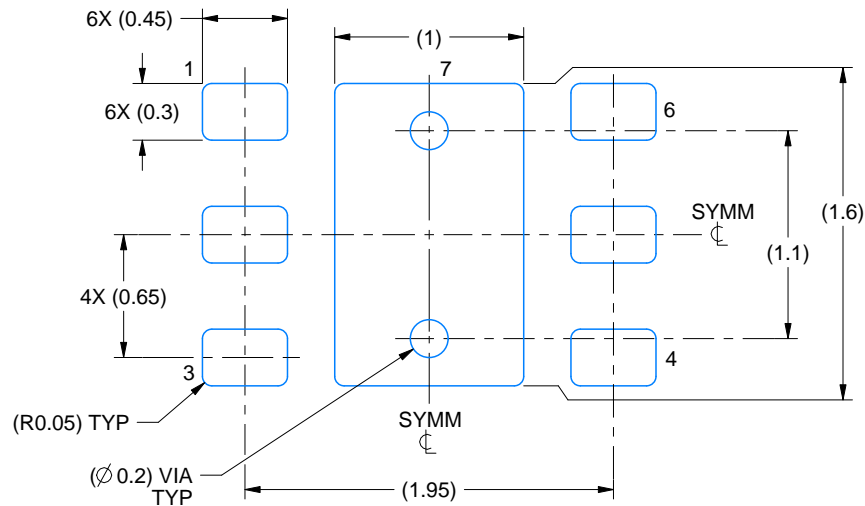
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.
4. Minimum 0.1 mm solder wetting on pin side wall. Available for wettable flank version only.

EXAMPLE BOARD LAYOUT

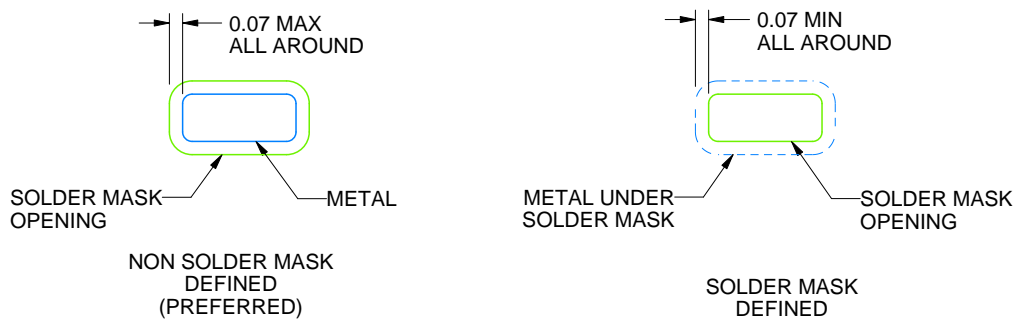
DRV0006A

WSON - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
SCALE:25X



SOLDER MASK DETAILS

4222173/C 11/2025

NOTES: (continued)

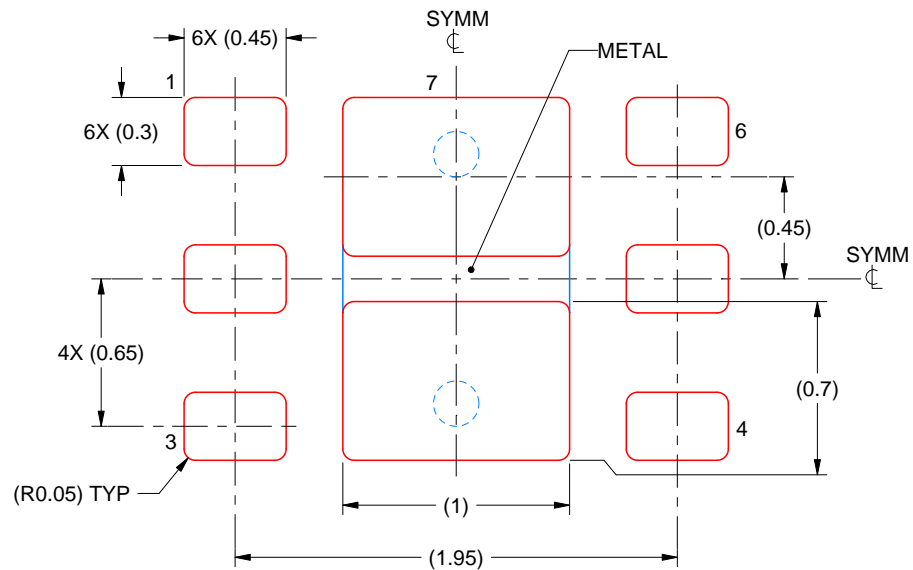
5. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
6. Vias are optional depending on application, refer to device data sheet. If some or all are implemented, recommended via locations are shown.

EXAMPLE STENCIL DESIGN

DRV0006A

WSON - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD #7
88% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:30X

4222173/C 11/2025

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

DRL0006A



PACKAGE OUTLINE

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



4223266/F 11/2024

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-293 Variation UAAD

EXAMPLE BOARD LAYOUT

DRL0006A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE
SCALE:30X



SOLDERMASK DETAILS

4223266/F 11/2024

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
7. Land pattern design aligns to IPC-610, Bottom Termination Component (BTC) solder joint inspection criteria.

EXAMPLE STENCIL DESIGN

DRL0006A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:30X

4223266/F 11/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

重要なお知らせと免責事項

TI は、技術データと信頼性データ (データシートを含みます)、設計リソース (リファレンス デザインを含みます)、アプリケーションや設計に関する各種アドバイス、Web ツール、安全性情報、その他のリソースを、欠陥が存在する可能性のある「現状のまま」提供しており、商品性および特定目的に対する適合性の黙示保証、第三者の知的財産権の非侵害保証を含むいかなる保証も、明示的または黙示的にかかわらず拒否します。

これらのリソースは、TI 製品を使用する設計の経験を積んだ開発者への提供を意図したものです。(1) お客様のアプリケーションに適した TI 製品の選定、(2) お客様のアプリケーションの設計、検証、試験、(3) お客様のアプリケーションに該当する各種規格や、その他のあらゆる安全性、セキュリティ、規制、または他の要件への確実な適合に関する責任を、お客様のみが単独で負うものとし、

上記の各種リソースは、予告なく変更される可能性があります。これらのリソースは、リソースで説明されている TI 製品を使用するアプリケーションの開発の目的でのみ、TI はその使用をお客様に許諾します。これらのリソースに関して、他の目的で複製することや掲載することは禁止されています。TI や第三者の知的財産権のライセンスが付与されている訳ではありません。お客様は、これらのリソースを自身で使用した結果発生するあらゆる申し立て、損害、費用、損失、責任について、TI およびその代理人を完全に補償するものとし、TI は一切の責任を拒否します。

TI の製品は、[TI の販売条件](#)、[TI の総合的な品質ガイドライン](#)、[ti.com](#) または TI 製品などに関連して提供される他の適用条件に従い提供されます。TI がこれらのリソースを提供することは、適用される TI の保証または他の保証の放棄の拡大や変更を意味するものではありません。TI がカスタム、またはカスタマー仕様として明示的に指定していない限り、TI の製品は標準的なカタログに掲載される汎用機器です。

お客様がいかなる追加条項または代替条項を提案する場合も、TI はそれらに異議を唱え、拒否します。

Copyright © 2026, Texas Instruments Incorporated

最終更新日 : 2025 年 10 月